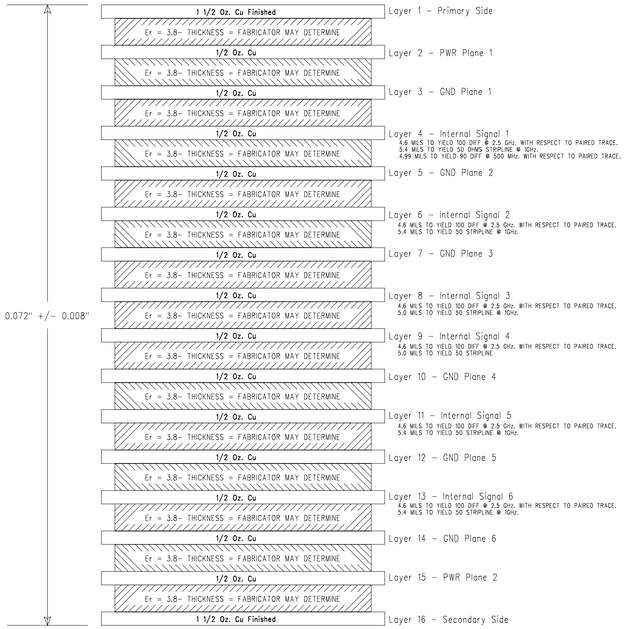

SIZE	QTY	SYM	PLATED	TOL
7.9	1874	+	YES	+2/-7.9 [Via In Pad]
8	600	X	YES	+2/-8
11.8	28	⊡	YES	+2/-11.8
27	14	◇	YES	+/-3
38	16	⊠	YES	+/-3
50	2	⊞	NO	+/-3
60	7	⊹	YES	+/-3
67	8	⊕	YES	+/-3
92	2	⊠	YES	+/-3
106	7	⊗	NO	+/-3

REVISIONS				
	REV.	DESCRIPTION	DATE	APPROVED

FABRICATION NOTES:

1. NUMBER OF LAYERS = 16
2. FABRICATE PER IPC-ML-6012B, CLASS 2.
3. INSPECT PER IPC-600 LATEST REVISION.
4. MATERIAL:
   - A. TYPE: FR408 OR EQUIVALENT
   - B. RAW Cu WEIGHT OUTER LAYERS: 1 Oz.
   - C. RAW Cu WEIGHT INNER SIGNAL LAYERS: 1/2 Oz.
   - D. RAW Cu WEIGHT INNER PLANE LAYERS: 1/2 Oz.
   - E. ☒HI Tg ☒RoHS ☐HALOGEN FREE ☐NON-CRITICAL ☐OTHER
5. PROCESSING:
   - A. COPPER THEIVING ALLOWED ON INNER LAYERS KEEPING A MINIMUM OF 0.500"
   - B. REMOVE ALL UNUSED PADS ON ARTWORK ON ALL INNER LAYERS.
   - C. ETCH DATE CODE AND UL RECOGNIZED VENDOR MARK ON SECONDARY SIDE.
6. IMPEDANCE:
   - A. USE REQUIRMENTS IN STACKUP. IF NONE, THEN STACKUP IS TOTAL THICKNESS AND LAYER STRUCTURE ONLY.
   - B. NON-CONTROLLED TRACES TO BE WITHIN 20% OF SPECIFIED APERTURE VALUE IN ARTWORK.
7. Cu PLATING:
   - A. UNLESS OTHERWISE SPECIFIED, HOLE DIMENSIONS ARE FOR FINISHED HOLES.
   - B. UNLESS OTHERWISE SPECIFIED, HOLE BARREL THICKNESS TO BE 0.001" MIN.
8. FINISH PLATING: FINISH ALL EXPOSED PADS WITH:
   - ☒ ELECTROLESS NICKEL/IMMERSION GOLD (ENIG)
   - ☐ IMMERSION SILVER (ENIG)
   - ☐ TIN/LEAD (HASL)
   - ☐ HARD GOLD OVER NICKEL 30u/80u
   - ☐ WHITE TIN
   - ☐ ORGANIC SOLDERABILITY PRESERVATIVE (OSP)
   - ☐ LEAD FREE HASL
9. SOLDERMASK:
   - A. LPI BLUE SOLDER MASK OVER BARE COPPER BOTH SIDES.
   - B. SOLDER MASK REGISTRATION TO BE WITHIN +/-.003" OF RELEVANT LAYER.
   - C. NO MASK TO APPEAR ON PADS
10. SILKSCREEN:
    - A. USE WHITE NON-CONDUCTIVE INK.
    - B. NO SILKSCREEN TO APPEAR ON PADS.
11. WARP AND TWIST NOT TO EXCEED .007 INCH/INCH.
12. MILLING:
    - A. ALL BOARD DIMENSIONS TO BE HELD TO WITHIN 0.005".
    - B. IF NO DIMENSIONS PRESENT, USE BOARD OUTLINE IN DD.PHO (THIS DRAWING) TO FEED DIRECTLY INTO MILLING PROCESSOR.
13. VIA SPECIAL FEATURES:
    - ☒ "VIA IN PAD" PLUGGED [NON-CONDUCTIVE] VIAS PLATED OVER FLAT AND FLUSH
    - ☐ "VIA IN PAD" PLUGGED VIAS [CONDUCTIVE] PLATED OVER FLAT AND FLUSH
    - ☐ PLUGGED VIAS ☐ TENTED VIAS PRIMARY SIDE ☐ BURIED VIAS
    - ☐ BLIND VIAS ☐ TENTED VIAS SECONDARY SIDE ☐ NONE

APPLICATION	
USED ON	NEXT ASSY.

MATERIAL: SEE NOTE
FINISH: SEE NOTE

DO NOT SCALE DRAWING

CONTRACT NO.

UNLESS OTHERWISE SPECIFIED

1. TOLERANCES:
   LINEAR = : 0.26 (.010)
   ANGULAR = : 0.50°
2. ALL DIMENSIONS ARE IN MM (INCHES).
3. INTERPRET DRAWING IN ACCORDANCE WITH DOD-STD-100.

DWN:	CRTS	9/11
CHK:		
P.E.:		
DES.ENG.:		
P.C.:		
Q.C.:		
C.M.:		
REL:		
MFG:		
ENG.MGR:		
OTHER:		
OTHER:		
OTHER:		

intersil.

TITLE:
FABRICATION DRAWING,
ADCMB-HSFMC-EV1Z

SIZE	CAGE CODE NO.	DRAWING NO.	REV:
D		ADCMB-HSFMC-EV1Z	C

SCALE: 1:1 SHEET 1 OF 1

{INT022}ADCMB-HSFMC-EV1 - Thu Sep 29 08:36:31 2011